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Silicon NPN Epitaxial

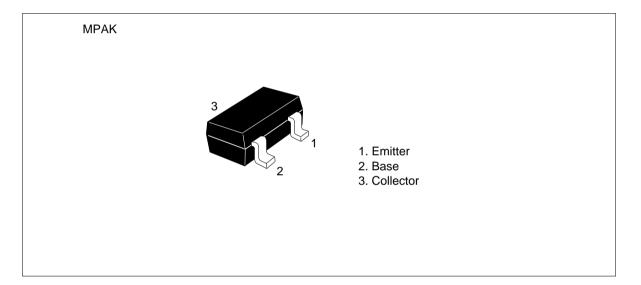


ADE-208-1064 (Z) 1st. Edition Mar. 2001

Application

Low frequency amplifier

Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

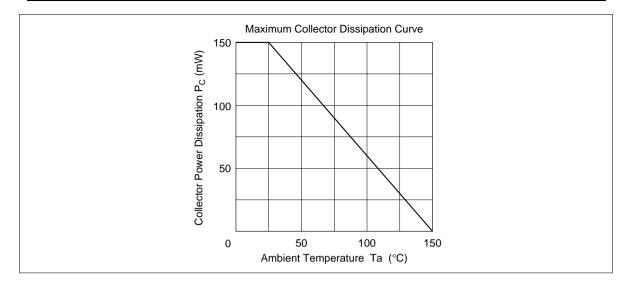
Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	55	V
Collector to emitter voltage	V _{CEO}	50	V
Emitter to base voltage	V _{EBO}	5	V
Collector current	Ι _c	100	mA
Collector power dissipation	Pc	150	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

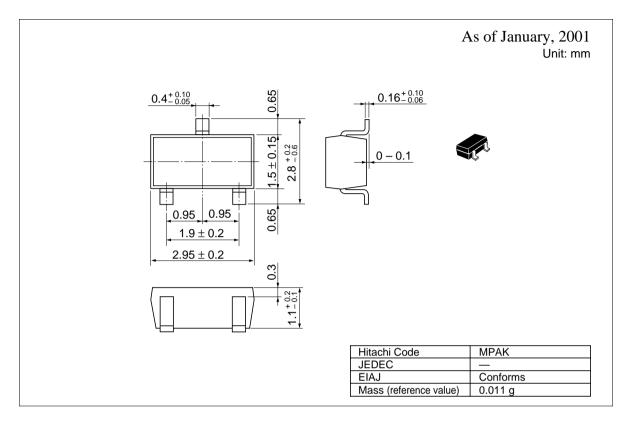
Item	Symbol	Min	Тур	Max	Unit	Test conditions	
Collector to base breakdown voltage	$V_{(\text{BR})\text{CBO}}$	55	-	_	V	$I_{c} = 10 \ \mu A, I_{e} = 0$	
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	50	_	_	V	$I_c = 1 \text{ mA}, R_{BE} =$	
Emitter to base breakdown voltage	$V_{\rm (BR)EBO}$	5	_	_	V	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$	
Collector cutoff current	I _{cbo}	_	—	0.5	μA	$V_{CB} = 30 \text{ V}, \text{ I}_{E} = 0$	
Emitter cutoff current	I_{EBO}	—	—	0.5	μA	$V_{EB} = 2 V, I_{C} = 0$	
DC current transfer ratio	h_{FE}^{*1}	250	—	1200		$V_{ce} = 12 \text{ V}, \text{ I}_{c} = 2 \text{ mA}$	
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.5	V	$I_{c} = 10 \text{ mA}, I_{B} = 1 \text{ mA}$	
Base to emitter voltage	V _{BE}	—	—	0.75	V	$V_{ce} = 12 \text{ V}, \text{ I}_{c} = 2 \text{ mA}$	
Note: 1. The 2SC2463 is grouped by h_{FE} as follows.							
Grade D E		F					
Mark DD D	E	DF					
h _{FE} 250 to 500 4	00 to 800	600 to	1200				

See characteristic curves of 2SC1345.

RENESAS



Package Dimensions



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